TECHNIQUE FOR ENHANCING ADHESION CAPABILITY OF HEAT SPREADERS IN MOLDED PACKAGES

ABSTRACT OF THE DISCLOSURE

Adhesion between a heat spreader (15) and a substance (19) to be adhered to the heat spreader can be enhanced by using thermal spray deposition or flame plasma deposition to apply a coating (23) to the heat spreader. The substance to be adhered is applied to the coated heat spreader. The technique can be used in all electrical circuit assemblies.

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This Sheet Has Been Replaced

